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Intel® 6321ESB I/O Controller




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Essentials

Product Collection	Intel® 5000 Series Chipsets
Code Name	Products formerly ESB2
Status	Launched
Launch Date	 Q1'06
TDP	 12.4 W
Recommended Customer Price	 N/A





Supplemental Information

Embedded Options Available	 Yes
Datasheet	View now

Expansion Options

PCI Support	 PCI (32/33) or PCI-X (66/100/133)
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I/O Specifications

USB Revision	 USB 2.0
# of USB Ports	8
Total # of SATA Ports	 6
Integrated LAN	 Dual 10/100/1000
Integrated IDE	 2 Channels

Package Specifications

Package Size	40mm x 40mm
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® ME Firmware Version	? Yes
Intel® Quick Resume Technology	? No
Intel® Quiet System Technology	? No
Intel® HD Audio Technology	? Yes
Intel® AC97 Technology	? Yes
Intel® Matrix Storage Technology	? No

Security & Reliability

Intel® Trusted Execution Technology	‡ ? No
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Ordering and Compliance

Downloads and Software

More support options for Intel® 6321ESB I/O Controller



Product Support



Downloads and Software



Support Community



Warranty and Replacement



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Refer to Datasheet for formal definitions of product properties and features.

“Announced” SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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